



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

SAH  
II 88  
7-6-01

Application Serial No. . . . . 09/784,234  
Filing Date . . . . . February 14, 2001  
Inventor . . . . . Shozo Nagano et al.  
Assignee . . . . . Honeywell International, Inc.  
Group Art Unit . . . . . Unknown 1742  
Examiner . . . . . Unknown IP  
Attorney's Docket No. . . . . 30-5000-(4015)-Div1  
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating  
Anodes, Metal Alloys For Use as a Conductive Interconnection in an  
Integrated Circuit, and Physical Vapor Deposition Targets

**SUPPLEMENTAL PRELIMINARY AMENDMENT**

To: Box Non-Fee Amendment  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Mark S. Matkin (Tel. 509-624-4276; Fax 509-838-3424)  
Wells, St. John, Roberts, Gregory & Matkin P.S.  
601 West First Avenue, Suite 1300  
Spokane, WA 99201-3828

Please enter the following amendments to the above-identified application.

**AMENDMENTS**

**In the Claims**

Cancel claims 31-33.

**New Claims**

Add new claims 60-66 as follows: